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conc. conductive pads formed on a portion of one of the faces near one of the sides and connected to the circuit, and

an integrally formed encapsulating mass which encapsulates all of the one face except in the region of the pads, all of the other face except in a region opposite to the region of the pads, and all of the sides.

15. The encapsulated circuit of claim 14, wherein the circuit includes electronic components mounted on both faces of the substrate and encapsulated in the encapsulating mass.

16. The encapsulated circuit of claim 15, wherein the conductive pads are formed on portions of the one face near the sides and the encapsulating mass encapsulates all of the one face except in the regions of the pads.

17. The encapsulated circuit of claim 16, wherein the conductive pads are formed on a portion of the other face near one of the sides and the encapsulating mass encapsulated all of the other face except the region of the pads.

18. The encapsulated circuit of claim 17, wherein the conductive pads are formed on portions of the other face near the sides and the encapsulating mass encapsulated all of the other face except the regions of the pads.--